

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HSM2836C

Silicon Epitaxial Planar Diode for High Speed Switching

RENESAS

ADE-208-030C (Z)

Rev.3
Mar. 2002

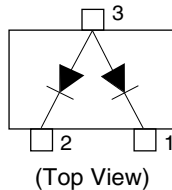
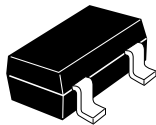
Features

- Fast recovery time.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSM2836C	A4	MPAK

Pin Arrangement



1. Cathode
2. Cathode
3. Anode

Absolute Maximum Ratings *¹

(Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	85	V
Reverse voltage	V_R	80	V
Average rectified current	I_O	100	mA
Peak forward current	I_{FM}	300	mA
Non-Repetitive peak forward surge current	I_{FSM}^{*2}	4	A
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes: 1. Per one device.

2. Within 1 μ s forward surge current.

Electrical Characteristics *

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	0.72	1.0	V	$I_F = 10$ mA
	V_{F2}	—	0.83	1.0		$I_F = 50$ mA
	V_{F3}	—	0.90	1.2		$I_F = 100$ mA
Reverse current	I_R	—	—	0.1	μ A	$V_R = 30$ V
Capacitance	C	—	2.5	4.0	pF	$V_R = 0$ V, $f = 1$ MHz
Reverse recovery time	t_{rr}	—	—	20.0	ns	$I_F = 10$ mA, $V_R = 6$ V, $R_L = 50$ Ω

Note: Per one device.

Main Characteristic

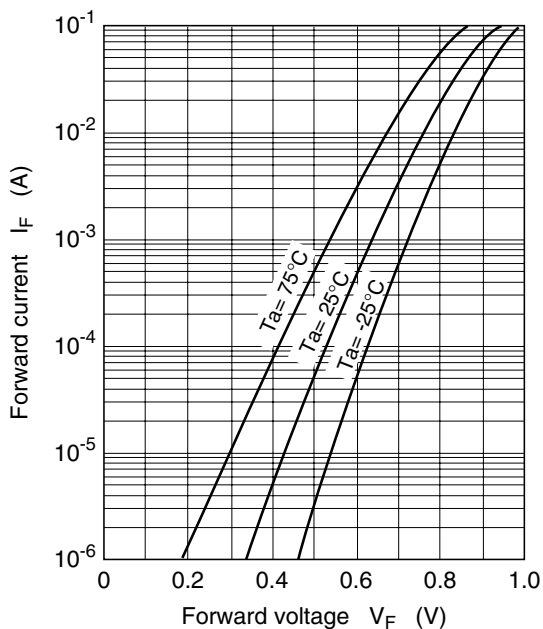


Fig.1 Forward current vs. Forward voltage

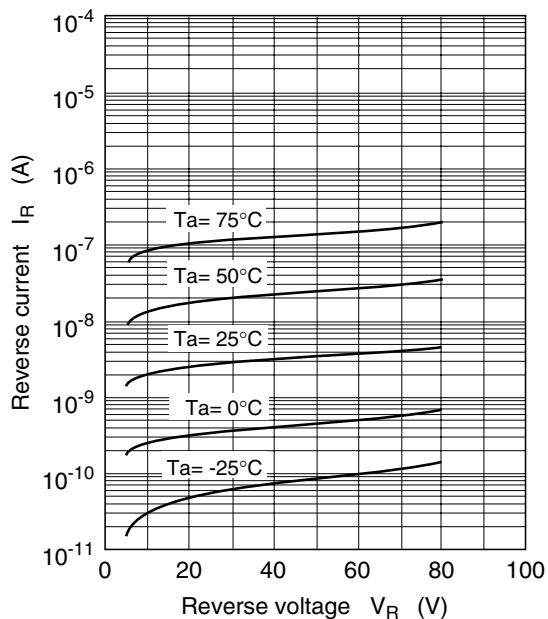


Fig.2 Reverse current vs. Reverse voltage

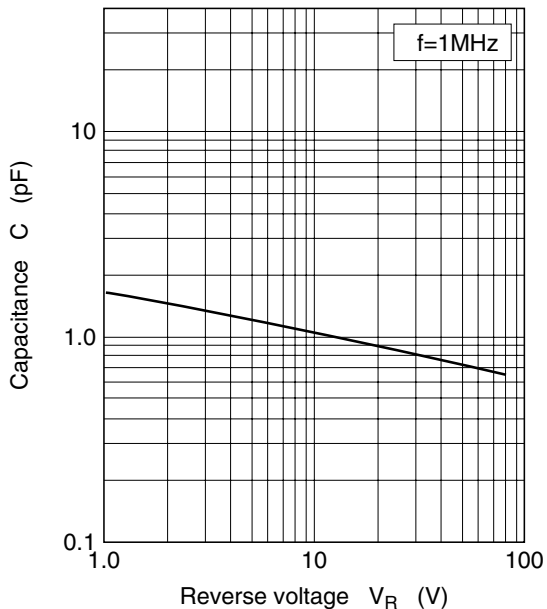
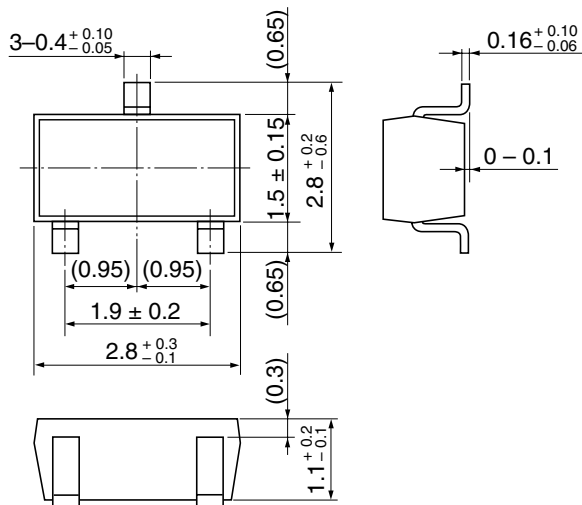


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

As of July, 2001
Unit: mm



Hitachi Code	MPAK
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.011 g

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Sales Offices

HITACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: <1> 3270-2111 Fax: (03) 3270-5109

URL <http://www.hitachisemiconductor.com/>

For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1>(408) 433-0223

Hitachi Europe Ltd.
Electronic Components Group
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 585200

Hitachi Europe GmbH
Electronic Components Group
Dornacher Straße 3
D-85622 Feldkirchen
Postfach 201, D-85619 Feldkirchen
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Asia Ltd.
Hitachi Tower
16 Collyer Quay #20-00
Singapore 049318
Tel : <65>-538-6533/538-8577
Fax : <65>-538-6933/538-3877
URL : <http://semiconductor.hitachi.com.sg>

Hitachi Asia Ltd.
(Taipei Branch Office)
4/F, No. 167, Tun Hwa North Road
Hung-Kuo Building
Taipei (105), Taiwan
Tel : <886>-(2)-2718-3666
Fax : <886>-(2)-2718-8180
Telex : 23222 HAS-TP
URL : <http://www.hitachi.com.tw>

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower
World Finance Centre,
Harbour City, Canton Road
Tsim Sha Tsui, Kowloon Hong Kong
Tel : <852>-(2)-735-9218
Fax : <852>-(2)-730-0281
URL : <http://semiconductor.hitachi.com.hk>

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